

ANNEX 3 TO TEST REPORT # EMCC-180541BGB, 2019-08-30**INTERNAL PHOTOGRAPHS OF EQUIPMENT UNDER TEST****EQUIPMENT UNDER TEST:**

Trade Name:	Edge FCR 3
Type/Model:	110012
Serial Number(s):	00001101
Application:	Edge Computing Device
FCC ID:	2ASE6EDGEFCR3
Manufacturer:	MYNXG Product GmbH
Address:	Friedhofstraße 72 63263 Neu-Isenburg GERMANY
Phone:	+49 911 990 876 22
E-Mail:	christian.winkelmeyr@mynxg.com

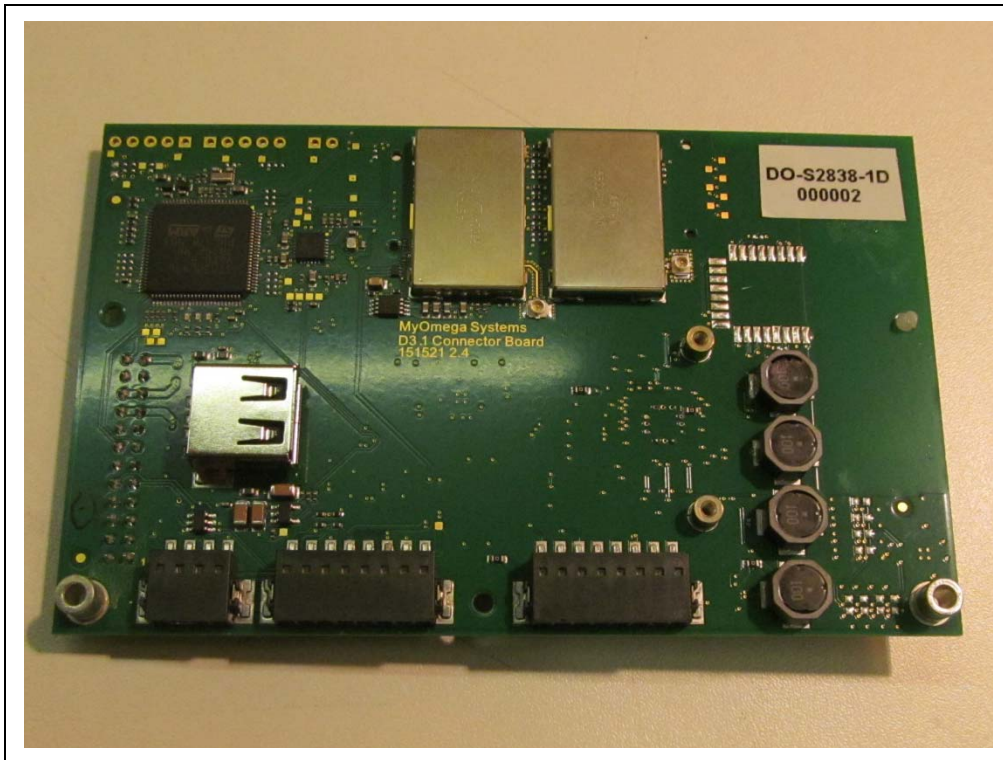
RELEVANT STANDARD(S) :	47 CFR § 15.247 KDB 558074 D01 15.247 Meas Guidance v05r02
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MEASUREMENT PROCEDURE: :	ANSI C63.10-2013
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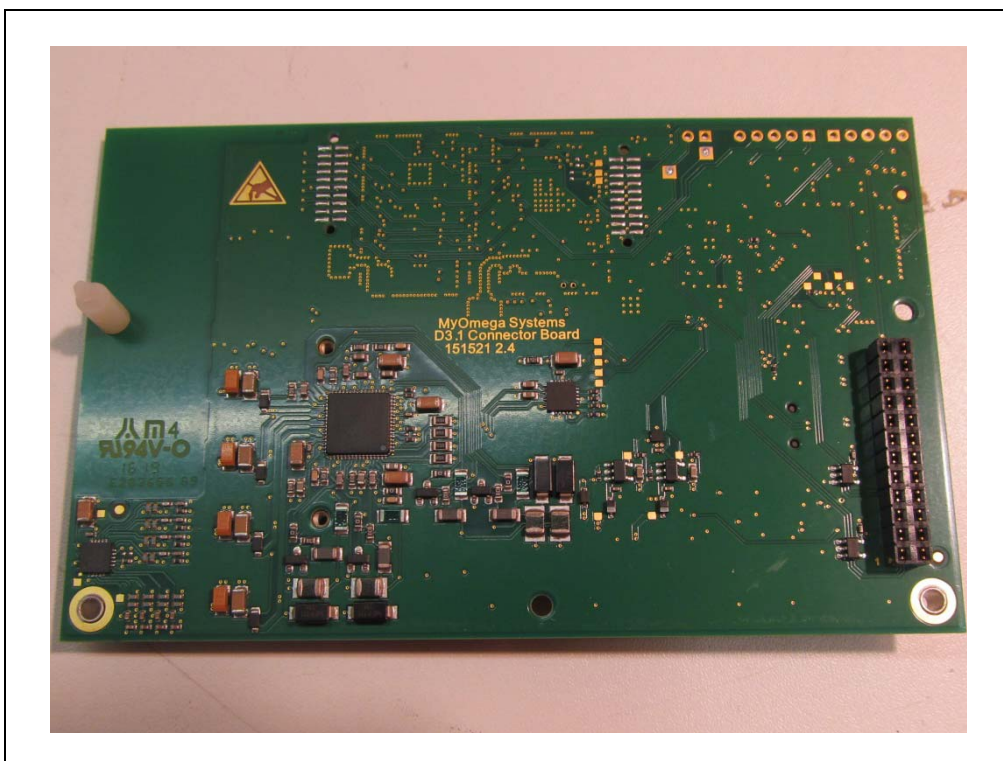
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Test on MYNXG Product GmbH 110012 to 47 CFR § 15.247 and KDB 558074 D01 15.247 Meas Guidance v05r02

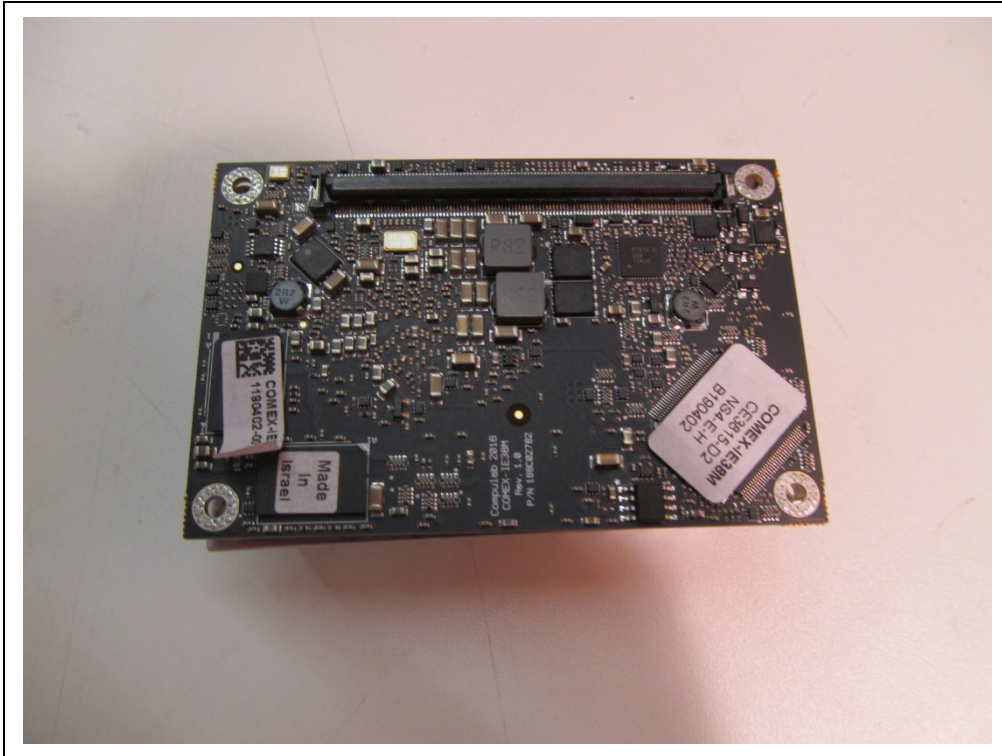


Photograph A3-1: D3.1 Connector Board Top

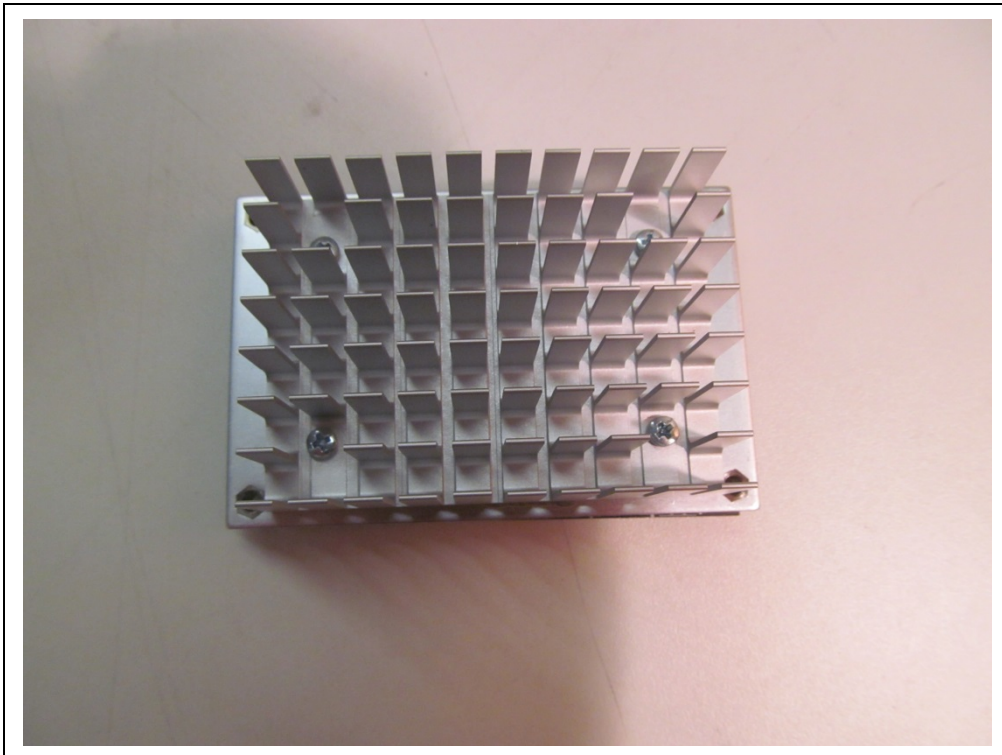


Photograph A3-2: D3.1 Connector Board Bottom

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Photograph A3-3: CPU Board Top

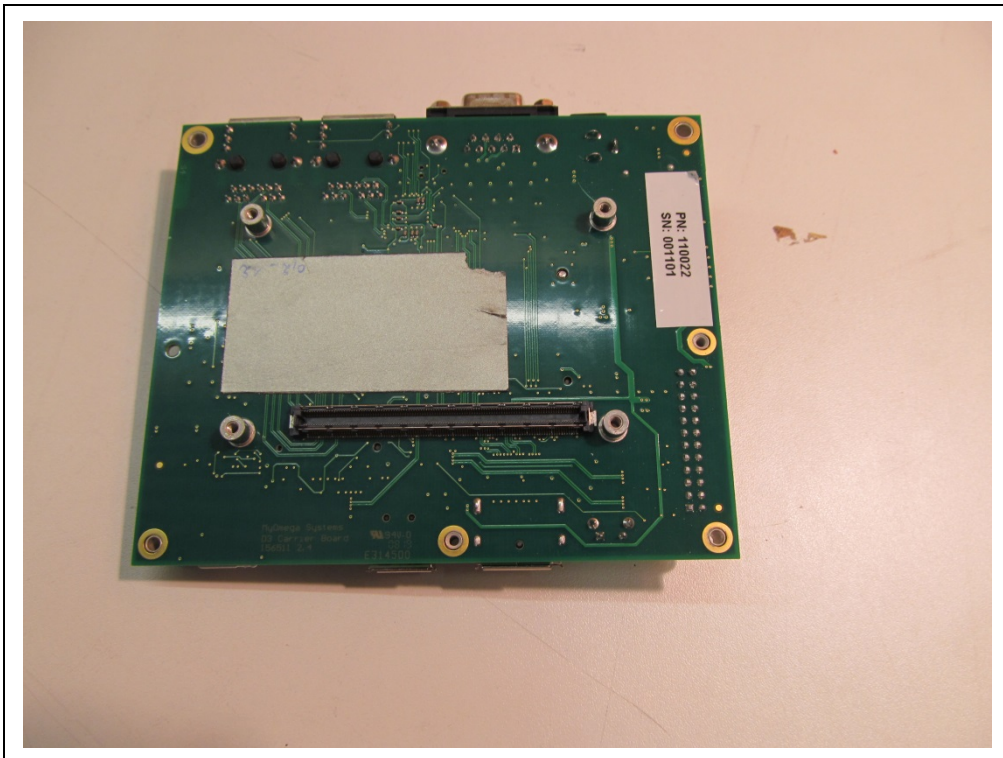


Photograph A3-4: CPU Board Bottom (with heatsink)

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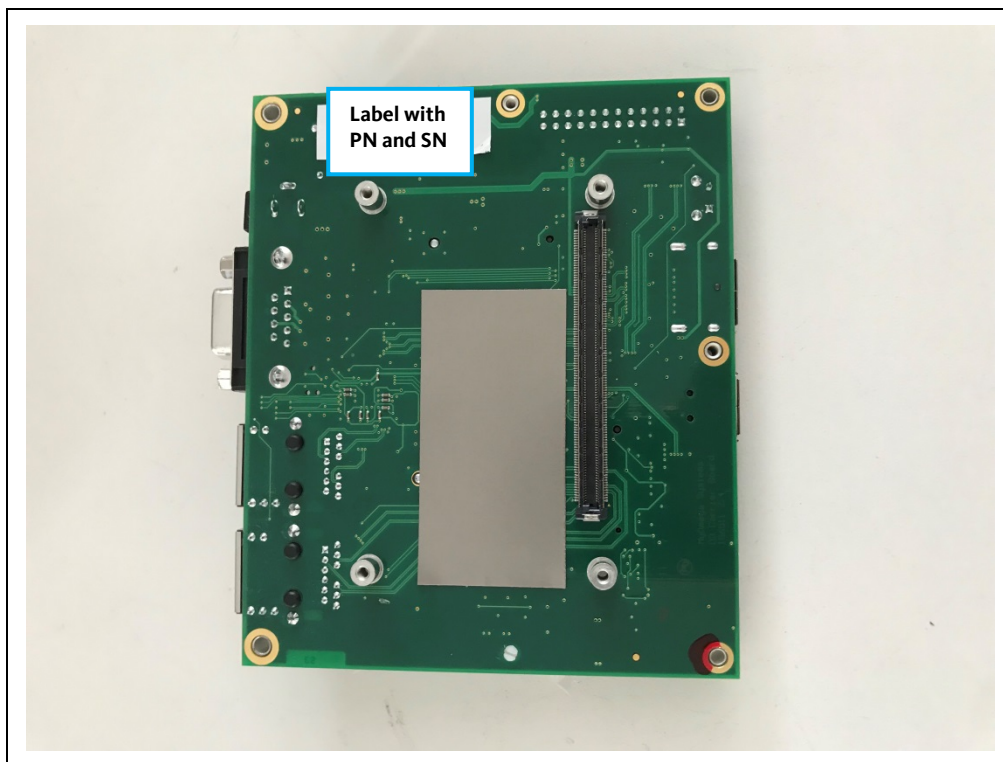


Photograph A3-5: D3 Carrier Board Top



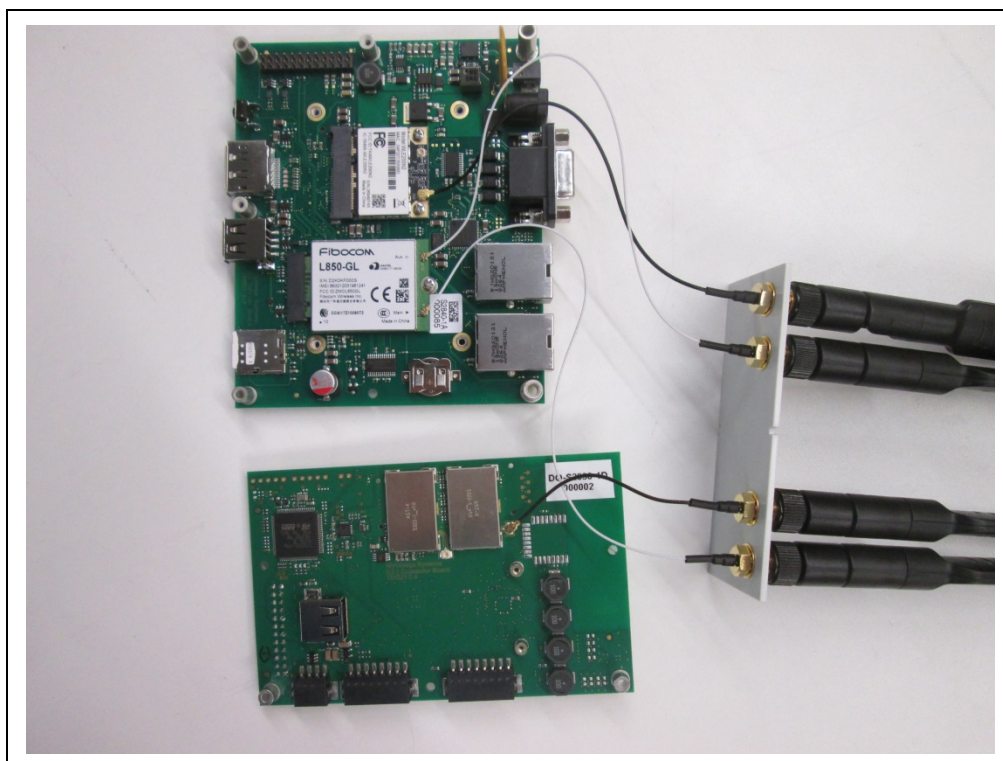
Photograph A3-6: D3 Carrier Board Bottom with adhesive shielding material

Test on MYNXG Product GmbH 110012 to 47 CFR § 15.247 and KDB 558074 D01 15.247 Meas Guidance v05r02



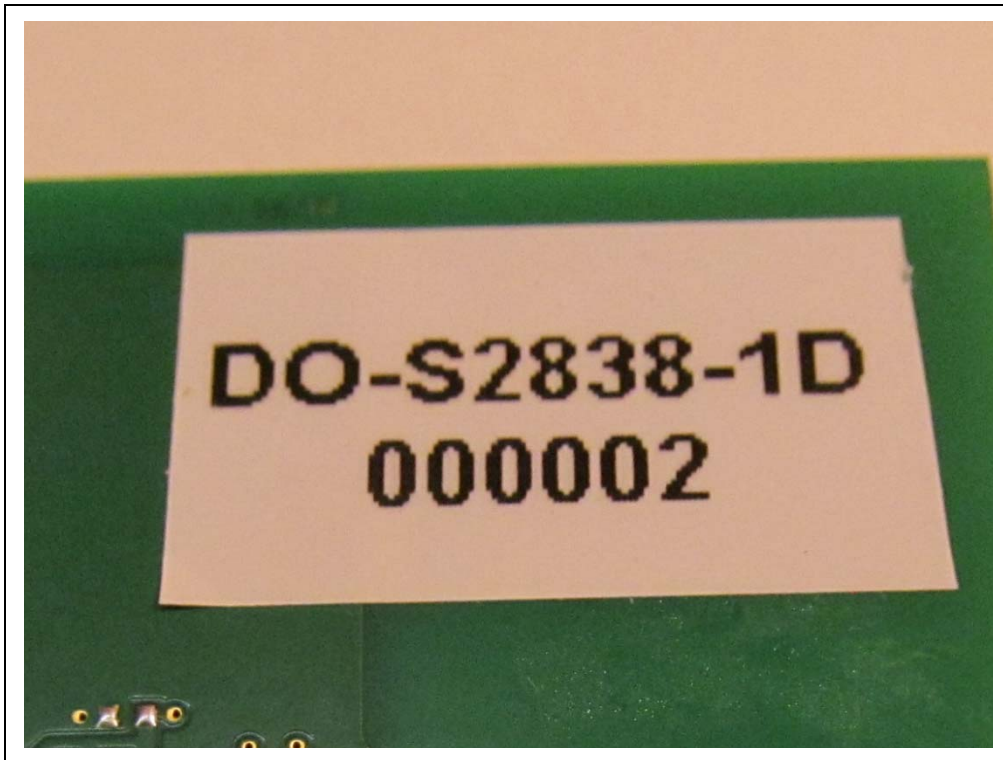
Photograph A3-7: Photo of production sample of D3 Carrier Board Bottom.

For information, only. Picture was delivered by customer. EUT was not used for testing.



Photograph A3-8: Connections of antennas

Test on MYNXG Product GmbH 110012 to 47 CFR § 15.247 and KDB 558074 D01 15.247 Meas Guidance v05r02

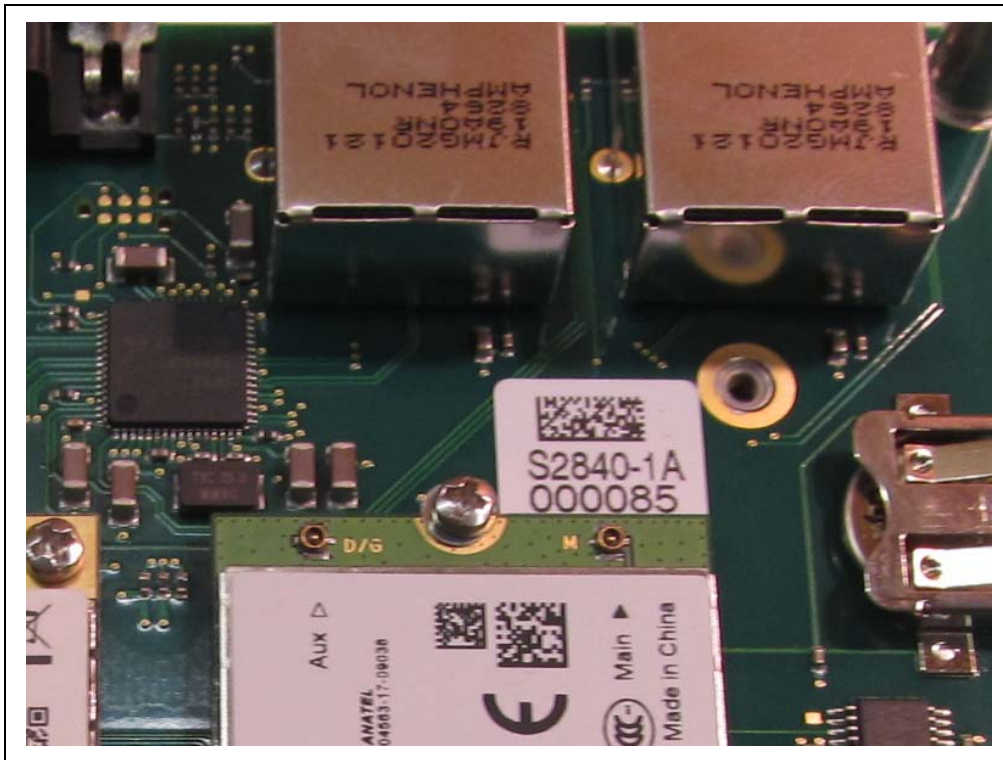


Photograph A3-9: Label of D3.1 Connector Board

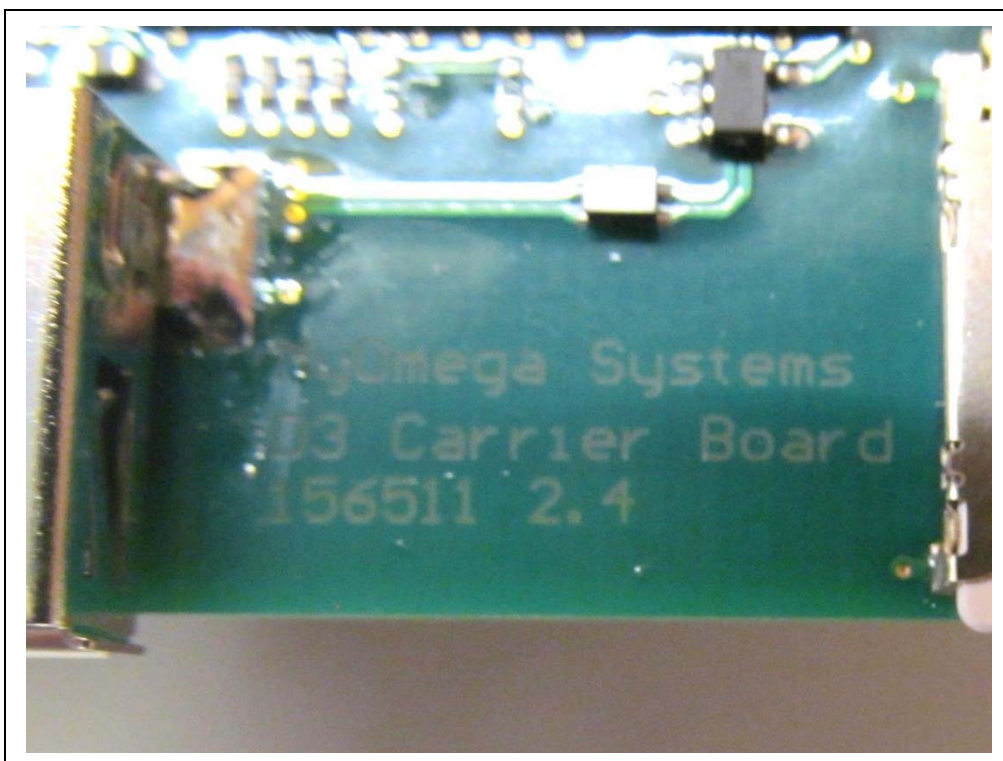


Photograph A3-10: Label of D3.1 Connector Board

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Photograph A3-11: Label of D3 Carrier Board



Photograph A3-12: Label of Label of D3 Carrier Board

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Photograph A3-13: Label of WIFI module (on D3 Carrier Board)

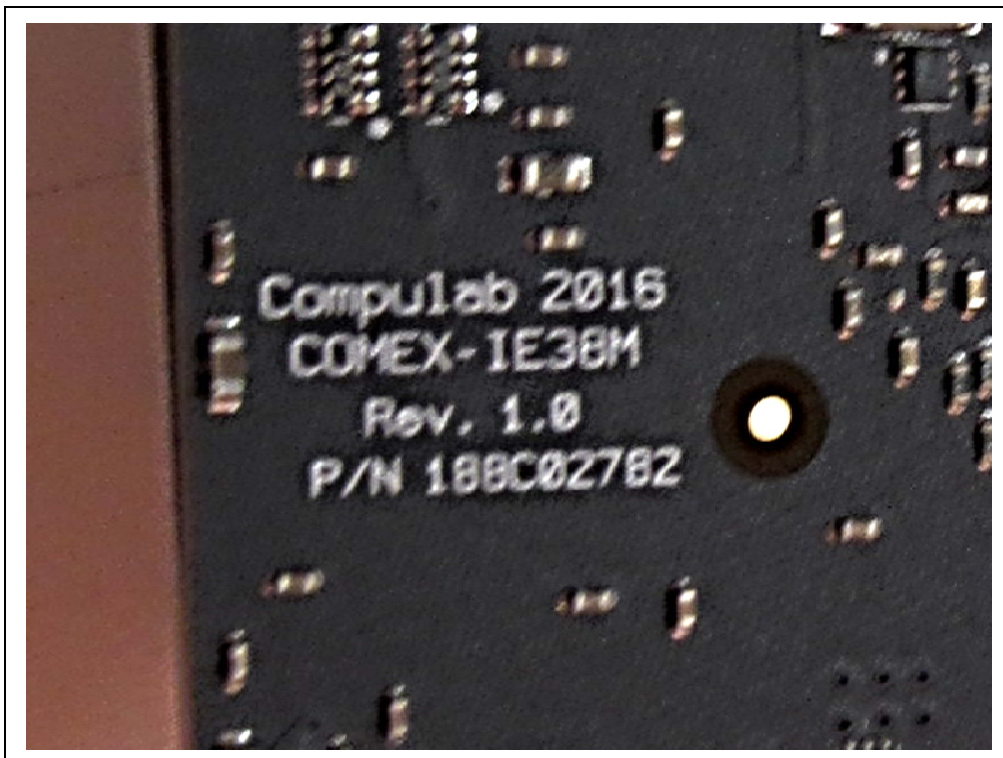


Photograph A3-14: Label of Cellular radio module (on D3 Carrier Board)

Test on MYNXG Product GmbH 110012 to 47 CFR § 15.247 and KDB 558074 D01 15.247 Meas Guidance v05r02



Photograph A3-15: Label of CPU Board



Photograph A3-16: Label of CPU Board